

## Automotive N-Channel 100 V (D-S) 175 °C MOSFET

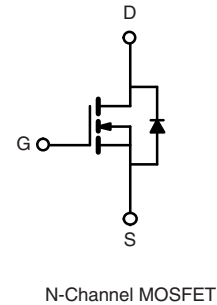
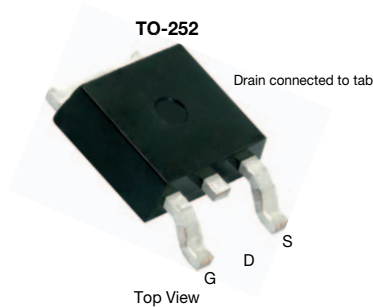
 AUTOMOTIVE  
GRADE

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

PRODUCT SUMMARY	
$V_{DS}$ (V)	100
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 10$ V	0.0150
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 4.5$ V	0.0190
$I_D$ (A)	30
Configuration	Single
Package	TO-252

### FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 %  $R_g$  and UIS tested
- AEC-Q101 qualified
- Material categorization:  
for definitions of compliance please see  
[www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	$V_{DS}$	100	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current	$I_D$	$T_C = 25$ °C <sup>a</sup>	30	A
		$T_C = 125$ °C	27	
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	30		
Pulsed Drain Current <sup>b</sup>	$I_{DM}$	120		
Single Pulse Avalanche Current	$I_{AS}$	L = 0.1 mH	34	
Single Pulse Avalanche Energy			$E_{AS}$	
Maximum Power Dissipation <sup>b</sup>	$P_D$	$T_C = 25$ °C	71	W
		$T_C = 125$ °C	23	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	$R_{thJA}$	50	°C/W	
Junction-to-Case (Drain)				

### Notes

- Package limited.
- Pulse test; pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %.
- When mounted on 1" square PCB (FR4 material).



SPECIFICATIONS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$		100	-	-	V
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$		1.5	-	2.5	
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$		-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 100\text{ V}$	-	-	1.0	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$	$V_{DS} = 100\text{ V}$ , $T_J = 125\text{ }^\circ\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$	$V_{DS} = 100\text{ V}$ , $T_J = 175\text{ }^\circ\text{C}$	-	-	250	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} \geq 5\text{ V}$	30	-	-	A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 30\text{ A}$	-	0.0120	0.0150	$\Omega$
		$V_{GS} = 10\text{ V}$	$I_D = 30\text{ A}$ , $T_J = 125\text{ }^\circ\text{C}$	-	-	0.0255	
		$V_{GS} = 10\text{ V}$	$I_D = 30\text{ A}$ , $T_J = 175\text{ }^\circ\text{C}$	-	-	0.0320	
		$V_{GS} = 4.5\text{ V}$	$I_D = 20\text{ A}$	-	0.0145	0.0190	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}$ , $I_D = 25\text{ A}$		-	58	-	S
<b>Dynamic <sup>b</sup></b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	-	1565	2100	$\text{pF}$
Output Capacitance	$C_{oss}$			-	800	1100	
Reverse Transfer Capacitance	$C_{rss}$			-	65	100	
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{GS} = 10\text{ V}$	$V_{DS} = 50\text{ V}$ , $I_D = 30\text{ A}$	-	26.5	40	$\text{nC}$
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			-	5.5	-	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			-	5.5	-	
Gate Resistance	$R_g$	$f = 1\text{ MHz}$		1.1	2.3	3.5	$\Omega$
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = 50\text{ V}$ , $R_L = 1.67\text{ }\Omega$ $I_D \cong 30\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_g = 1\text{ }\Omega$		-	7	15	$\text{ns}$
Rise Time <sup>c</sup>	$t_r$			-	19	30	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			-	18	30	
Fall Time <sup>c</sup>	$t_f$			-	59	95	
<b>Source-Drain Diode Ratings and Characteristics <sup>b</sup></b>							
Pulsed Current <sup>a</sup>	$I_{SM}$			-	-	120	A
Forward Voltage	$V_{SD}$	$I_F = 30\text{ A}$ , $V_{GS} = 0\text{ V}$		-	0.94	1.5	V

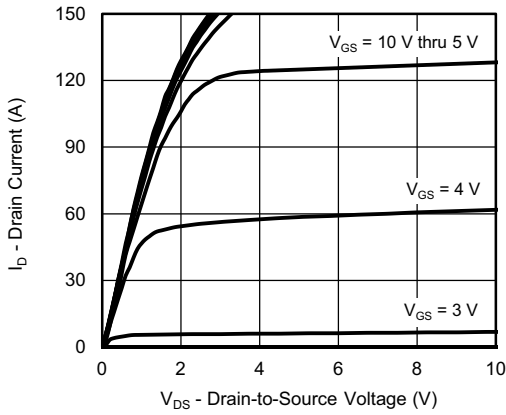
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.  
c. Independent of operating temperature.

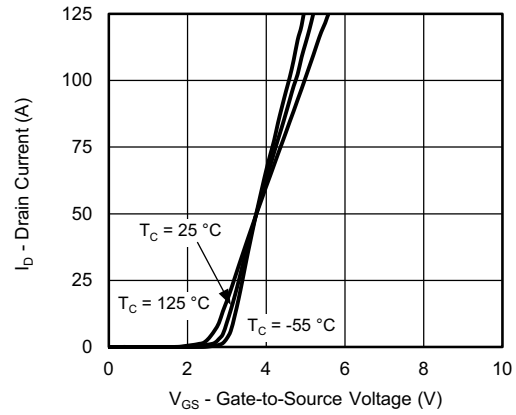
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



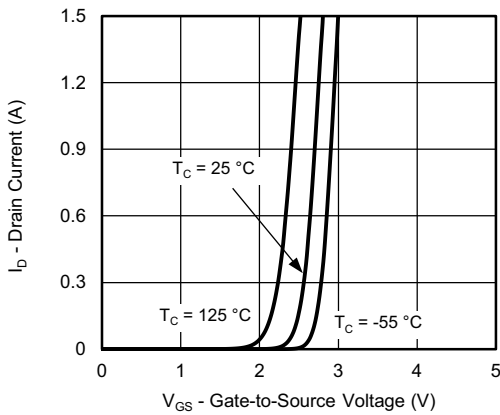
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



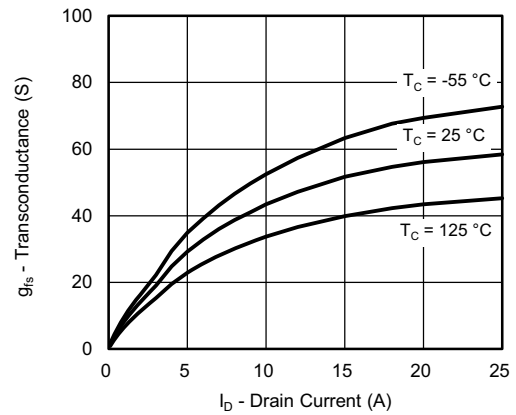
Output Characteristics



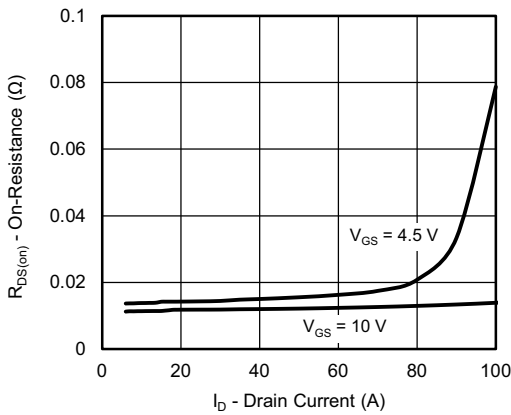
Transfer Characteristics



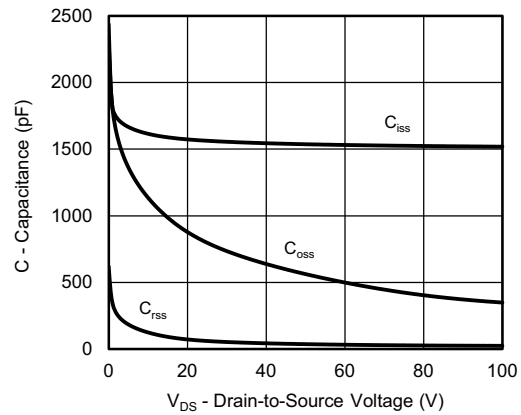
Transfer Characteristics



Transconductance



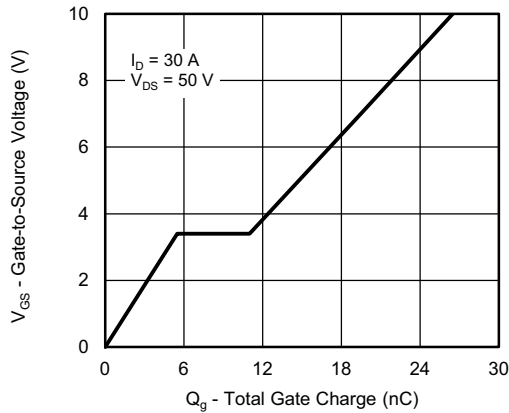
On-Resistance vs. Drain Current



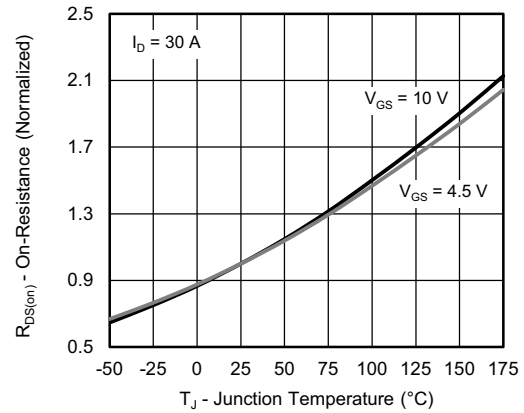
Capacitance



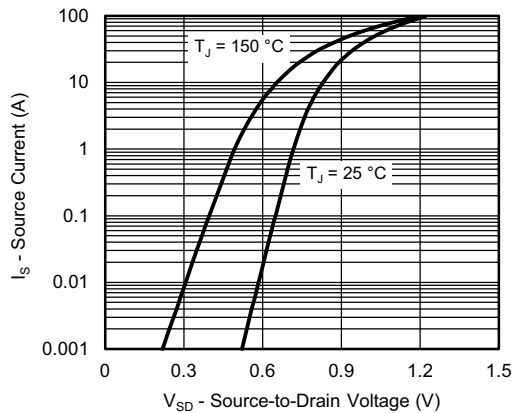
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



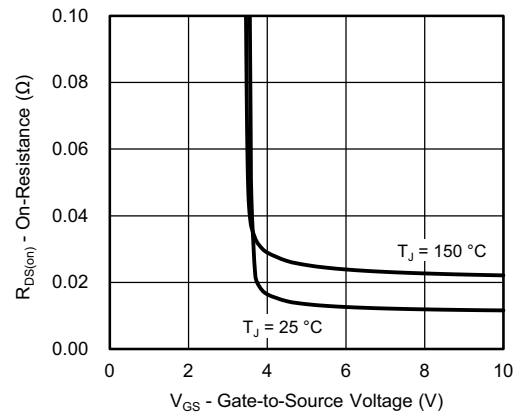
Gate Charge



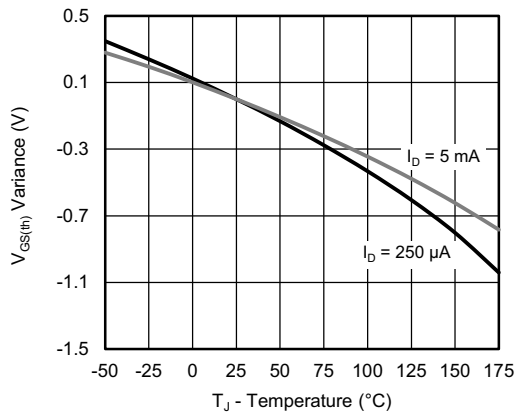
On-Resistance vs. Junction Temperature



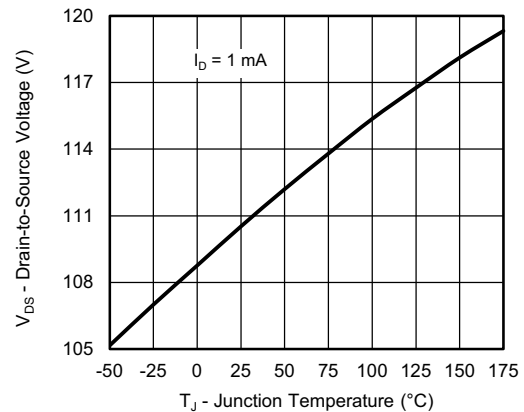
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



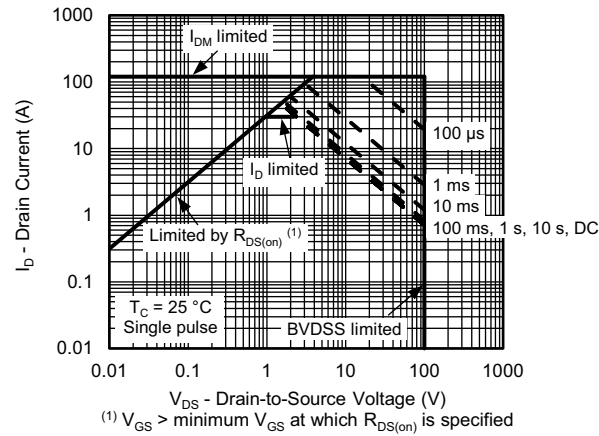
Threshold Voltage



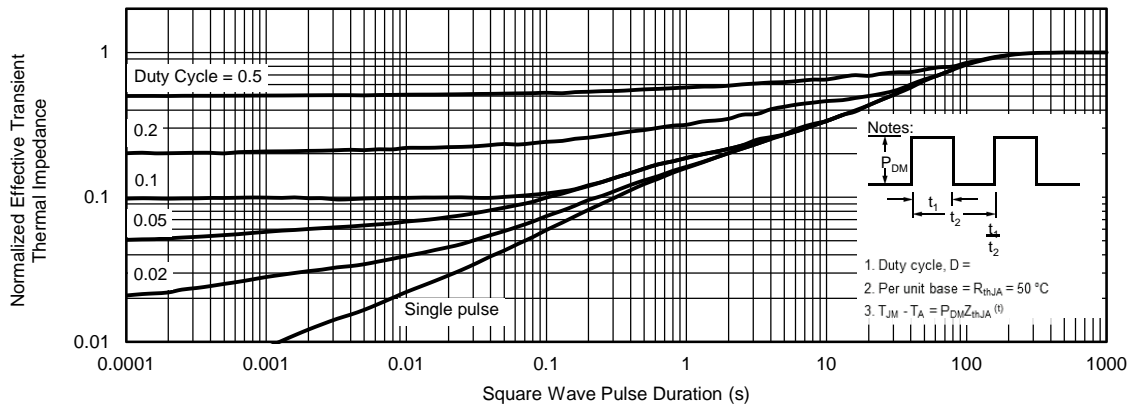
Drain Source Breakdown vs. Junction Temperature



**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



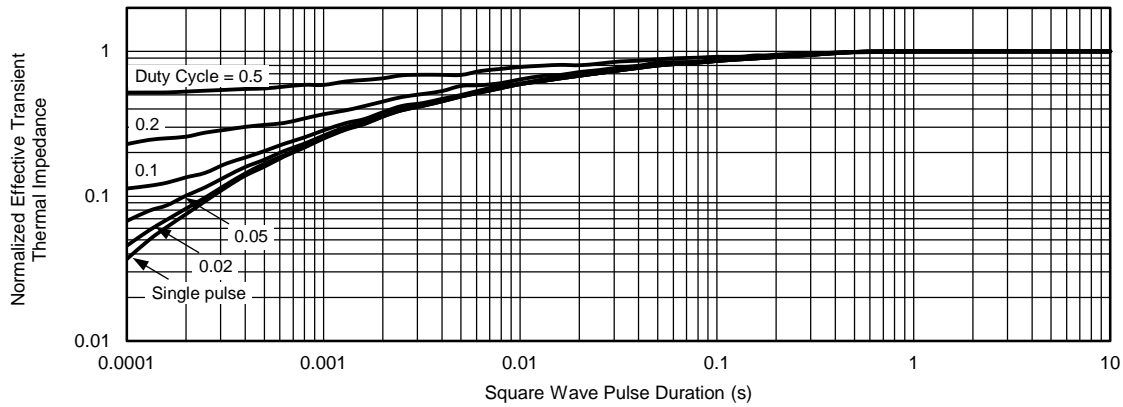
**Safe Operating Area**



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Case**

**Note**

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction to Case (25 °C)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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DPAK / TO-252 and Reverse DPAK

Ordering codes for the SQ rugged series power MOSFETs in the DPAK / TO-252 and Reverse DPAK packages:

Table with 3 columns: DATASHEET PART NUMBER, OLD ORDERING CODE a, NEW ORDERING CODE. Lists various MOSFET part numbers and their corresponding ordering codes.

Note

a. Old ordering code is obsolete and no longer valid for new orders



### TO-252AA Case Outline



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
C	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	4.10	-	0.161	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
H	9.40	10.41	0.370	0.410
e	2.28 BSC		0.090 BSC	
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.01	1.52	0.040	0.060
ECN: T13-0592-Rev. A, 02-Sep-13				
DWG: 6019				

**Note**

- Dimension L3 is for reference only.



## RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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